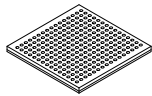


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

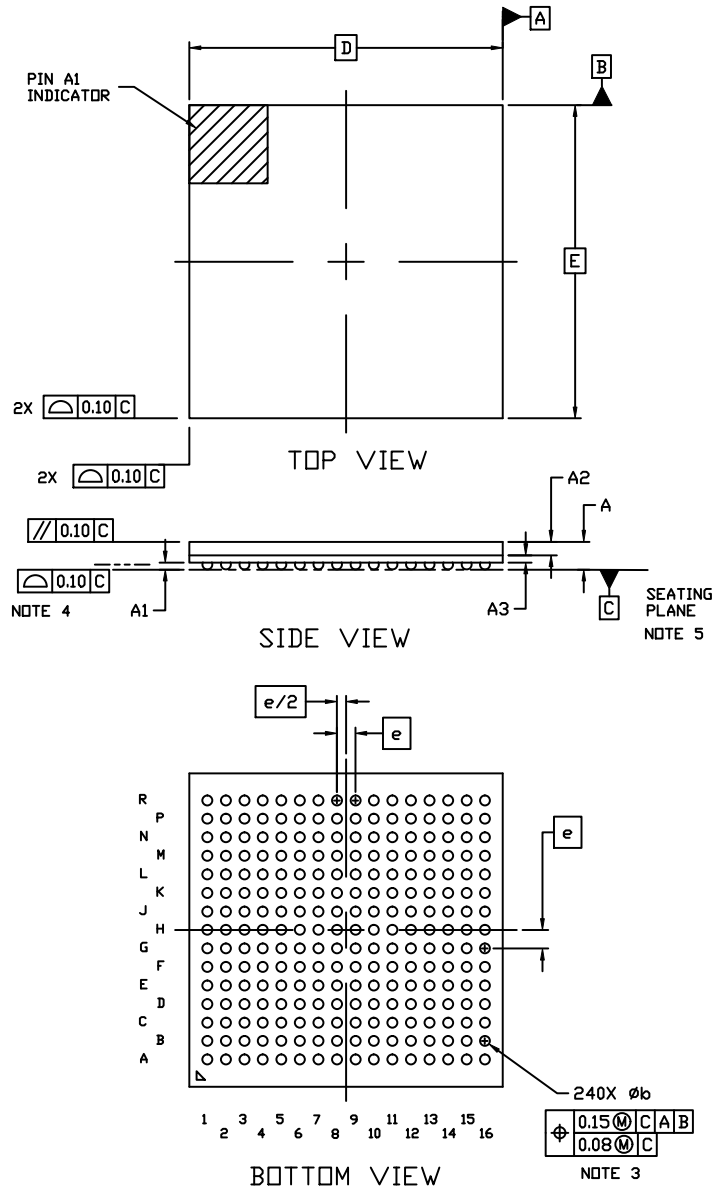
ON Semiconductor®



LFBGA240, 11x11
CASE 566EY
ISSUE A

DATE 05 FEB 2020

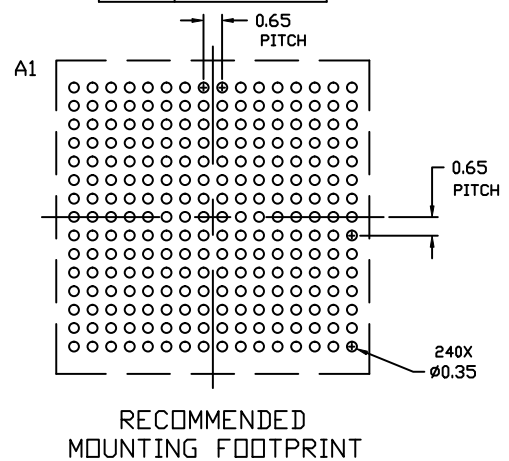
SCALE 1:1



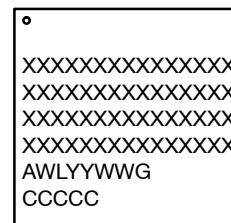
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.31
A1	0.20	0.30
A2	0.70	REF
A3	0.26	REF
b	0.30	0.40
D	11.00	BSC
E	11.00	BSC
e	0.65	BSC



GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package
- CC = Country of Origin

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DESCRIPTION:	LFBGA240, 11X11	PAGE 1 OF 1

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